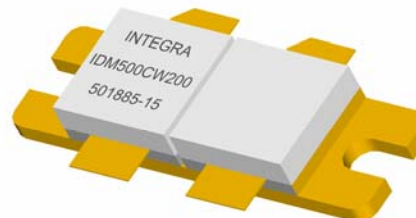


UHF-Band RF Power MOSFET

The high power transistor part number IDM500CW200 is designed for VHF/UHF-Band systems operating at 1-500 MHz. Operating at CW conditions, this dual MOSFET device supplies a minimum of 200 watts of power across the instantaneous operating bandwidth of 1-500 MHz. All devices are 100% screened for large signal RF parameters.



TYPICAL DATA TYPICAL DATA TYPICAL DATA TYPICAL DATA

Device	Freq (MHz)	V _{DD} (V)	P _{IN} (W)	IRL (dB)	P _{OUT} (W)	Gain (dB)	I _D (A)	η_d (%)
D5228-1	200	28	8.5	15	224	14.2	11.9	67.3
D5228-1	300	28	14.9	24	246	12.2	13.1	67
D5228-1	400	28	20	29	256	11.1	13.3	68.5
D5228-1	500	28	21	28	213	10.1	12.0	63.4

Silicon MOSFET

- High Power Gain
- Superior thermal stability

Class AB Operation

- Gate biased to I_{DQ}=2x100mA

Configuration

- Common Source

Gold Metal

- Maximum Reliability

BeO Package

- Unmatched Thermal Reliability

Epoxy Sealed Lid

- Gross Leak Qualified

RF Test Fixture

- Narrowband
- Matched to 50 Ω
- Long-term Correlation
- 100% Device RF Screening
- No External Tuning required

MAXIMUM RATINGS

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
BD	Drain-Source Voltage	V_{DS}	--	80	V	--
BD	Gate-Source Voltage	V_{GS}	--	20	V	--
BD	Storage Temperature Range	T_{STG}	-55	+200	°C	--
BD	Operating Junction Temperature Range	T_J	-55	+200	°C	--
Note						
Screen 'BD' = parameter qualified By Design.						

THERMAL CHARACTERISTICS

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
BD	Thermal Resistance	$R_{TH(JC)}$	--	0.46	°C/W	$V_{CC}=28V$, $I_{DQ}=2x100mA$, $T_F=25\pm5^\circ C$, $P_{OUT}=200W$
Note						
Screen 'BD' = parameter qualified By Design.						

PROCESSING SPECIFICATIONS

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
100%	DC Wafer Probe	--	--	--	--	Per Integra specification.
Q1	Wafer DC and RF Qualification	--	--	--	--	Per Integra specification.
LM	Wire Bond Strength	--	--	--	--	Line monitor per Integra specification.
100%	Pre-cap visual inspection	--	--	--	--	Per Integra specification
100%	Gross leak test	--	--	--	--	MIL-STD-750D, Method 1071, Test Condition C
Note						
Screen 'Q1' = parameter is qualified by assembly and test of 3 pieces minimum per wafer.						
Note						
Screen 'LM' = parameter is qualified by assembly line monitor.						

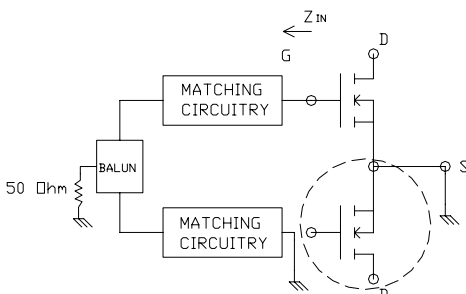
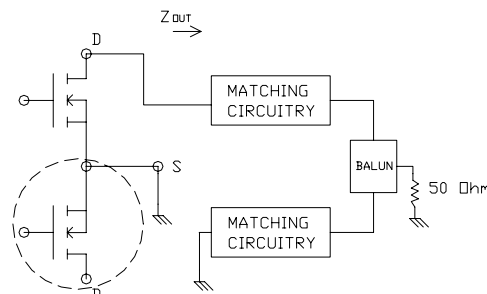
DC ELECTRICAL CHARACTERISTICS

Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
100%	Drain-Source Breakdown Voltage	BV_{DSS}	70	--	V	$I_D = 40mA$, $V_{GS} = 0V$, $T_F = 25\pm5^\circ C$
100%	Drain Leakage Current (each side)	I_{DSS}	--	100	μA	$V_{DS} = 28V$, $V_{GS} = 0V$, $T_F = 25\pm5^\circ C$
100%	Gate Threshold Voltage 2 (each side)	V_{GSTH2}	1.5	--	V	$I_D = 30mA$, $V_{GS} = 10V$, $T_F = 25\pm5^\circ C$

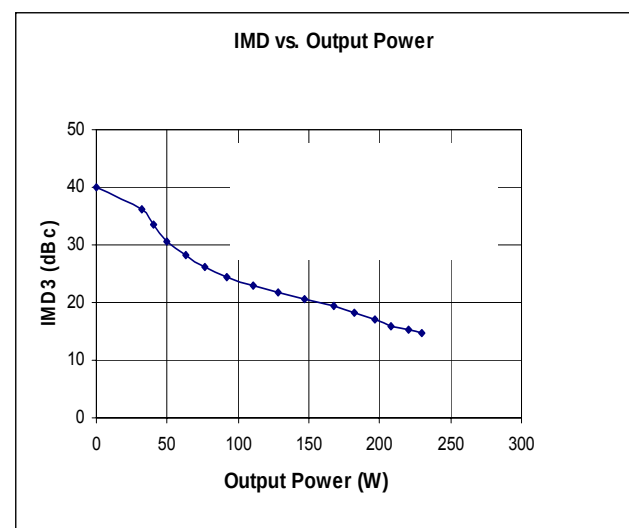
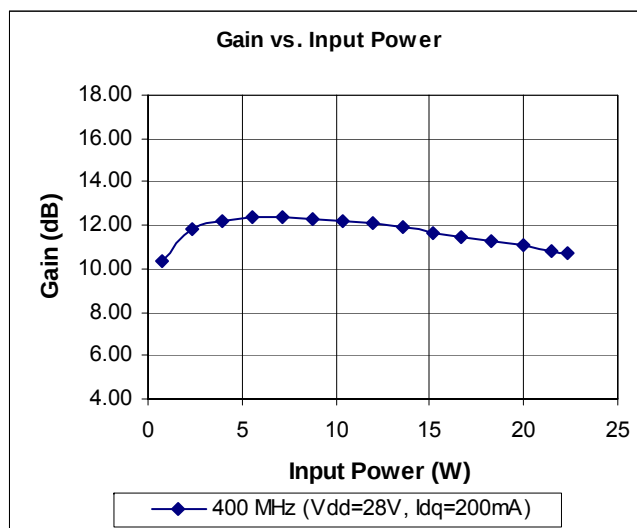
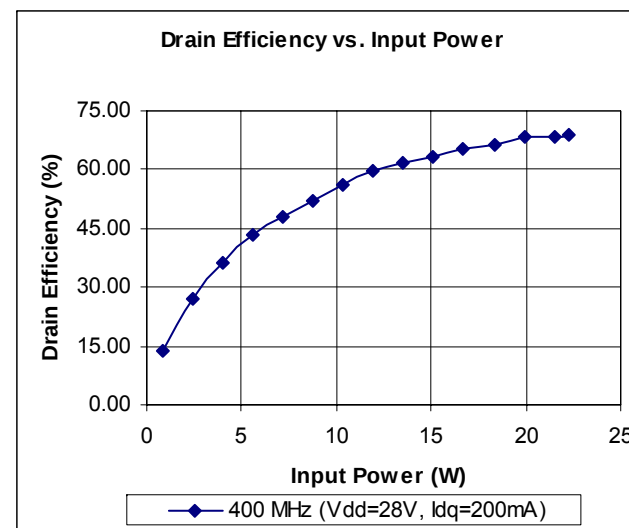
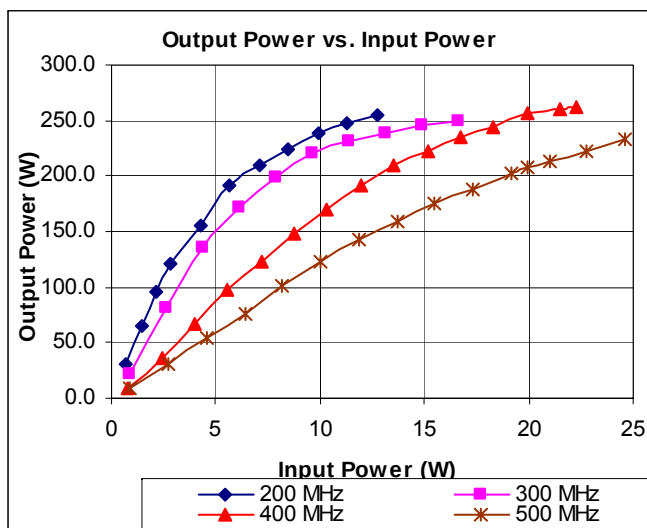
RF ELECTRICAL CHARACTERISTICS

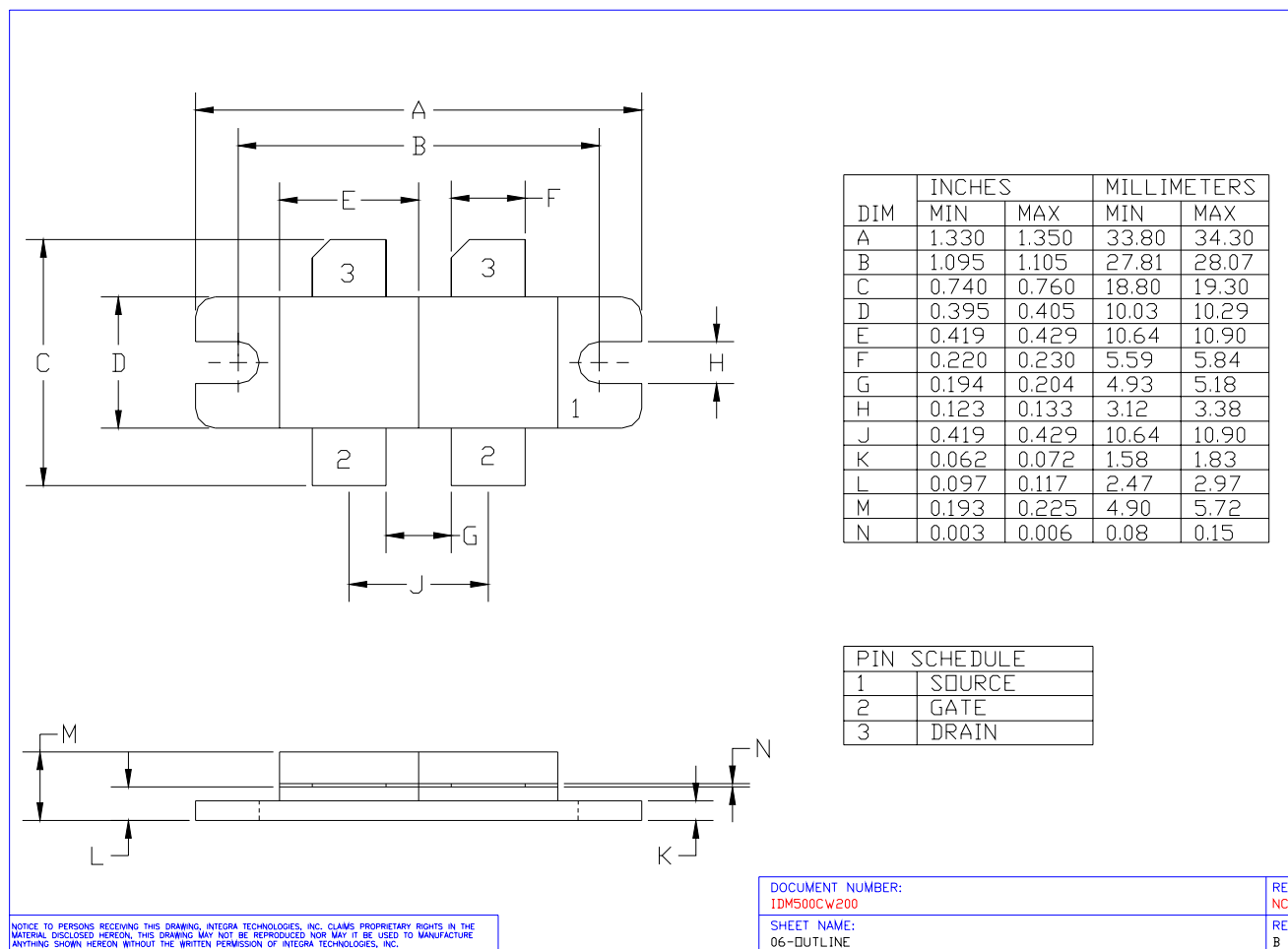
Screen	Parameter	Symbol	Min	Max	Units	Test Conditions
100%	Input Return Loss	IRL	10		dB	$V_{DD}=28V$, $I_{DQ}=2 \times 100mA$, $T_F=25 \pm 5^\circ C$, $P_{IN}=20W$, $F=400MHz$
100%	Output Power	P_O	200		W	$V_{DD}=28V$, $I_{DQ}=2 \times 100mA$, $T_F=25 \pm 5^\circ C$, $P_{IN}=20W$, $F=400MHz$
100%	Drain Efficiency ($P_O/I_D/V_{DD}$)	N_D	50		%	$V_{DD}=28V$, $I_{DQ}=2 \times 100mA$, $T_F=25 \pm 5^\circ C$, $P_{IN}=20W$, $F=400MHz$
						$V_{DD}=28V$, $I_{DQ}=2 \times 100mA$, $T_F=25 \pm 5^\circ C$, $P_{IN}=20W$, $F=400MHz$
BD	Input Capacitance	C_{ISS}		240	pF	$V_{DD}=28V$, $V_{GS}=0V$, $F=1MHz$
BD	Output Capacitance	C_{OSS}		120	pF	$V_{DD}=28V$, $V_{GS}=0V$, $F=1MHz$
BD	Reverse Transfer Capacitance	C_{RSS}		15	pF	$V_{DD}=28V$, $V_{GS}=0V$, $F=1MHz$
Note 2	T_F = Device flange temperature.					

RF TEST FIXTURE IMPEDANCE CHARACTERISTICS

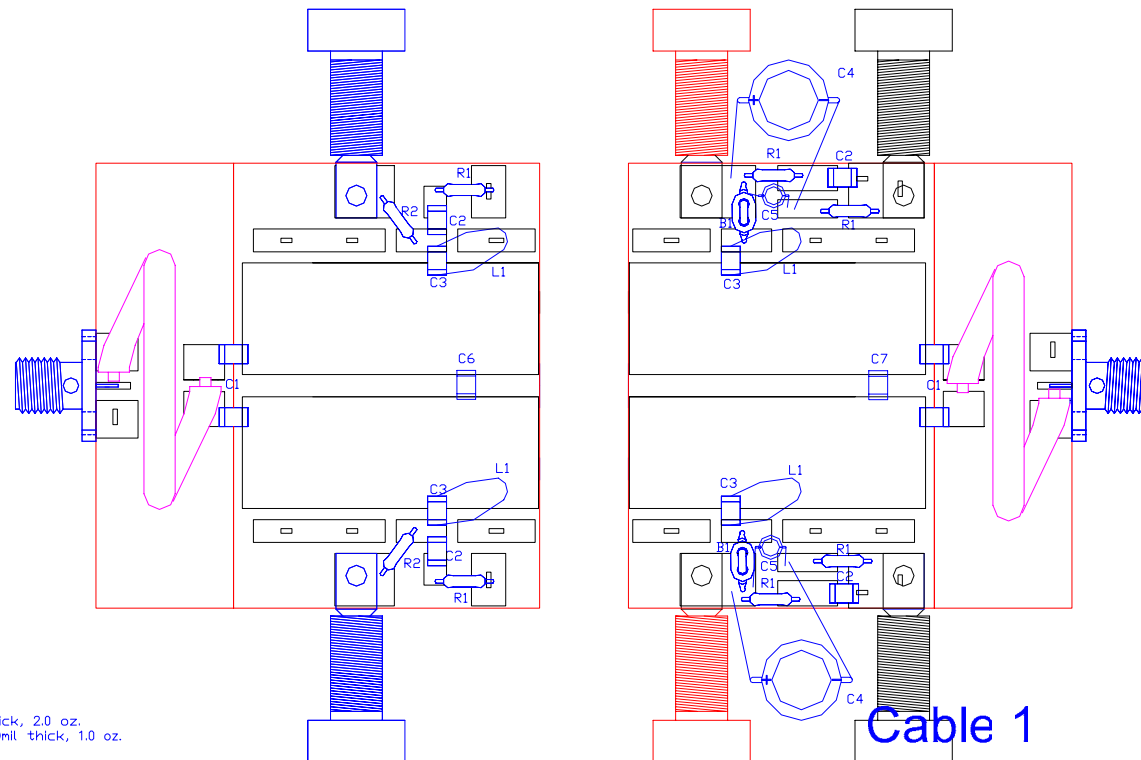
Frequency (MHz)	$Z_{IF} (\Omega)$	$Z_{OF} (\Omega)$
200	$9.56 + j8.82$	$7.20 - j5.98$
300	$2.02 + j0.46$	$7.92 - j5.60$
400	$1.10 - j1.44$	$3.64 - j1.82$
500	$0.72 - j1.48$	$1.76 - j2.28$
Impedance Definition		

Note : Input and output impedances are measured from gate to gate and drain to drain respectively.



PACKAGE DIMENSIONAL OUTLINE DRAWING

RF TEST FIXTURE (400 MHz)

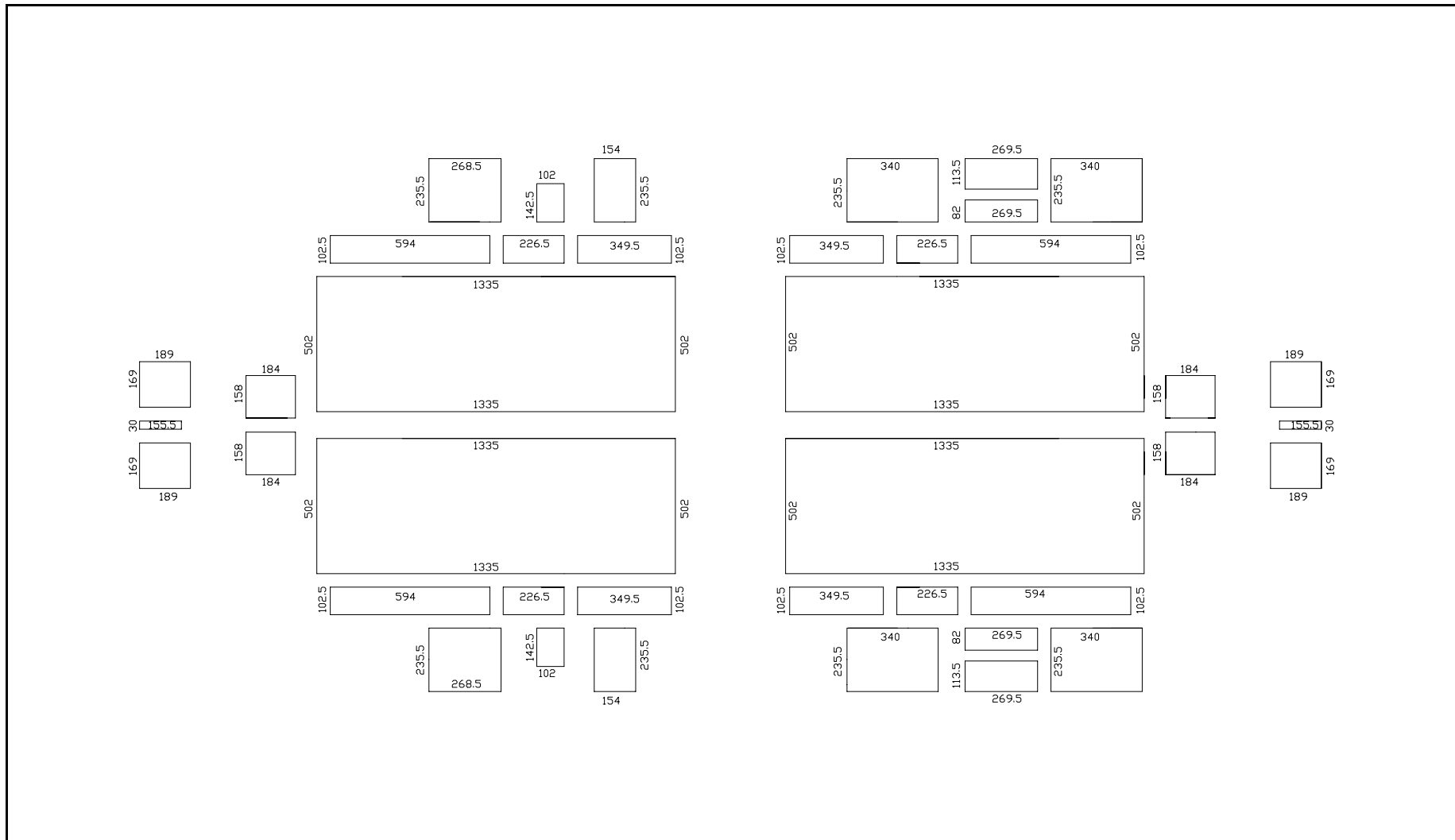


PARTS LIST

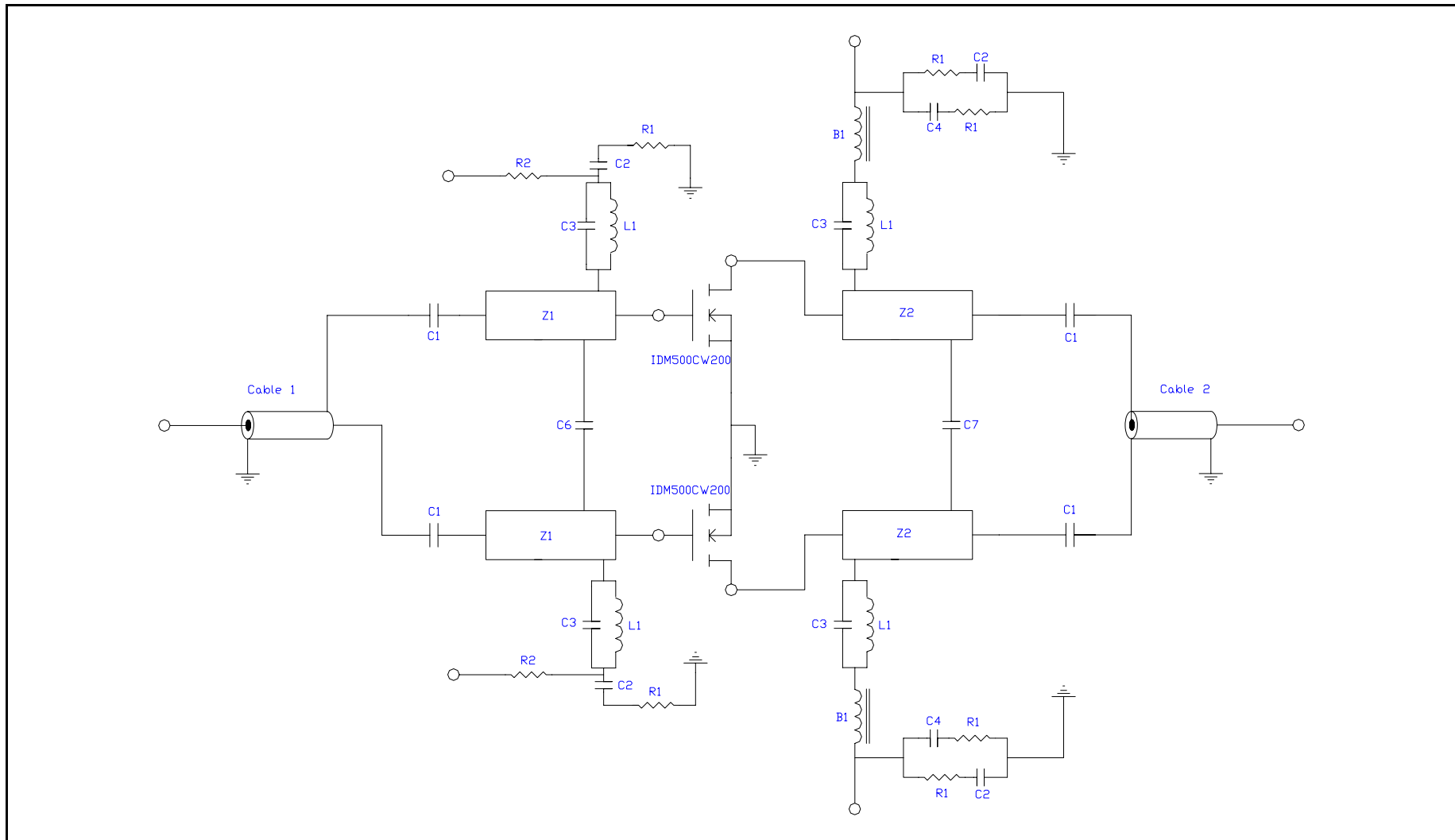
PC Board Type:
 Board A : ROGERS RT5880, 10mil thick, 2.0 oz.
 Board B : ROGERS RT6010.2LMNS, 10mil thick, 1.0 oz.
 Input PC Board Carrier (2")
 output PC Board Carrier (2")
 RF Connector: DS #2052-5636-02
 Banana Jack Black - 2 place
 Banana Jack Red - 2 place
 Banana Jack Blue - 2 place
 C1 : 300pF ATC 100B chip capacitor
 C2 : 4700 pF ATC 700B chip capacitor
 C3 : 10pF ATC 100B chip capacitor
 C4 : 68uF 63V
 C5 : 2.2uF 50V
 C6 : 39pF ATC 100B chip capacitor
 C7 : 27pF ATC 100B chip capacitor
 R1 : 10 Ohm resistor
 B1 : Ferronics Inc. Ferrite Bead 12-340-J
 L1 : Wire 18 TC, 1.4 inch
 Cable 1 : Micro-coax UT-141C-15, 2.8 inch
 Cable 2 : Micro-coax UT-141C-15, 4.1 inch

Cable 1

CIRCUIT DIMENSIONS (UNIT: MILS)



ELECTRICAL SCHEMATIC



DEFINITIONS

Data Sheet Status	
Proposed Specification	This data sheet contains proposed specifications.
Preliminary Specification	This data sheet contains specifications based on preliminary measurements and data.
Product Specification	This data sheet contains final product specifications.
Maximum Ratings	
Stress above one or more of the maximum ratings may cause permanent damage to the device. These are maximum ratings only. Operation of the device at these or at any other conditions above those given in the characteristics sections of the specification is not implied. Exposure to maximum values for extended periods of time may affect device reliability.	

WARNING

Product and environmental safety - toxic materials
This product contains beryllium oxide. The product is entirely safe provided that the BeO base is not damaged. All persons who handle, use or dispose of this product should be aware of its nature and of the necessary safety precautions. After use, dispose of as chemical or special waste according to the regulations applying at the location of the user. It must never be thrown out with general or domestic waste.

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